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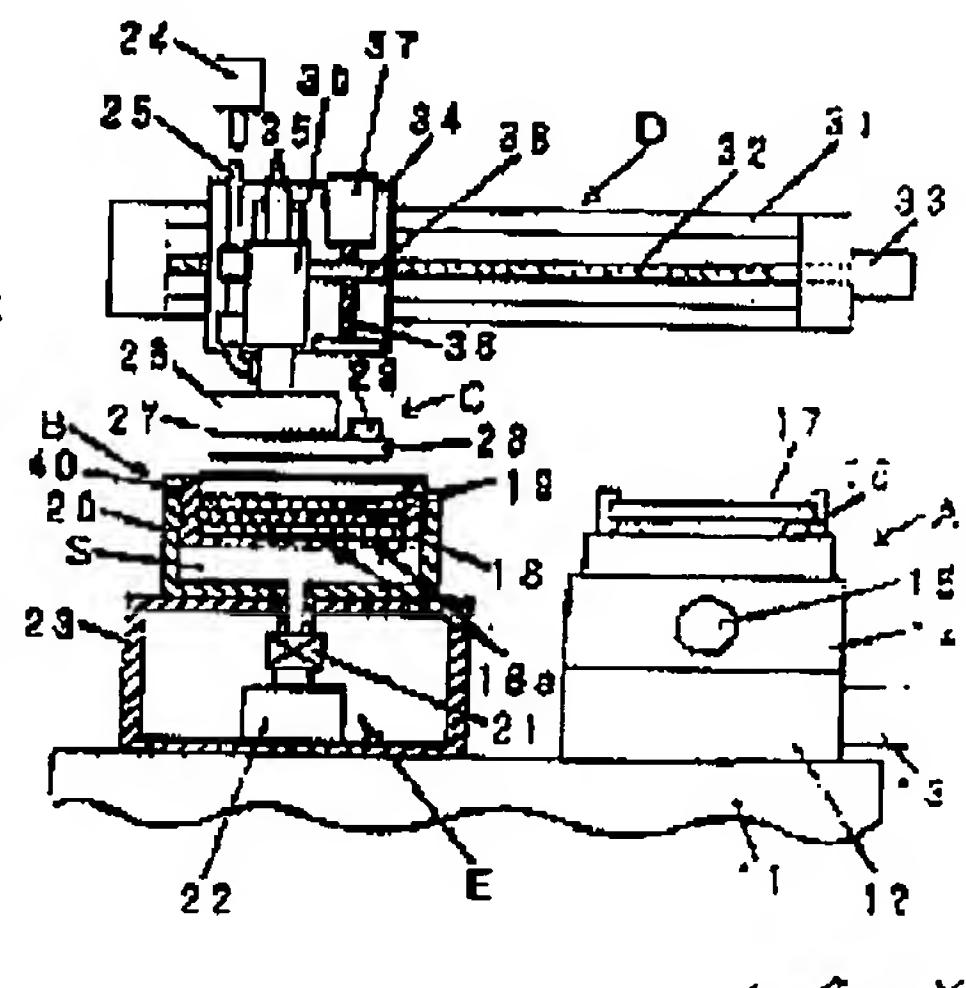
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(54) DEVICE FOR TRANSLOCATING SOLDER BALL AND METHOD THEREFOR

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a device and method for translocating solder balls by which the solder balls are vacuum sucked surely one by one into a suction hole and then the vacuum sucked balls are surely moved to a work when the solder balls are vacuum sucked into the suction hole and moved to the work.

SOLUTION: Equipped are a positioning table A to position the work 17, a ball gathering place B to accomodate a plurality of solder balls 19, a gas supply means E to supply gas to the ball gathering place B, a suction head C equipped with a suction hole which vacuum sucks and picks up the solder balls 19 from the ball gathering place B and then drops off the solder balls 19 and moves them to the work 17, a transferring means D to move the suction head C between the ball gathering place B and the work 17, and further a vibrator 29 to vibrate a suction pad 28 of the suction head C.



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